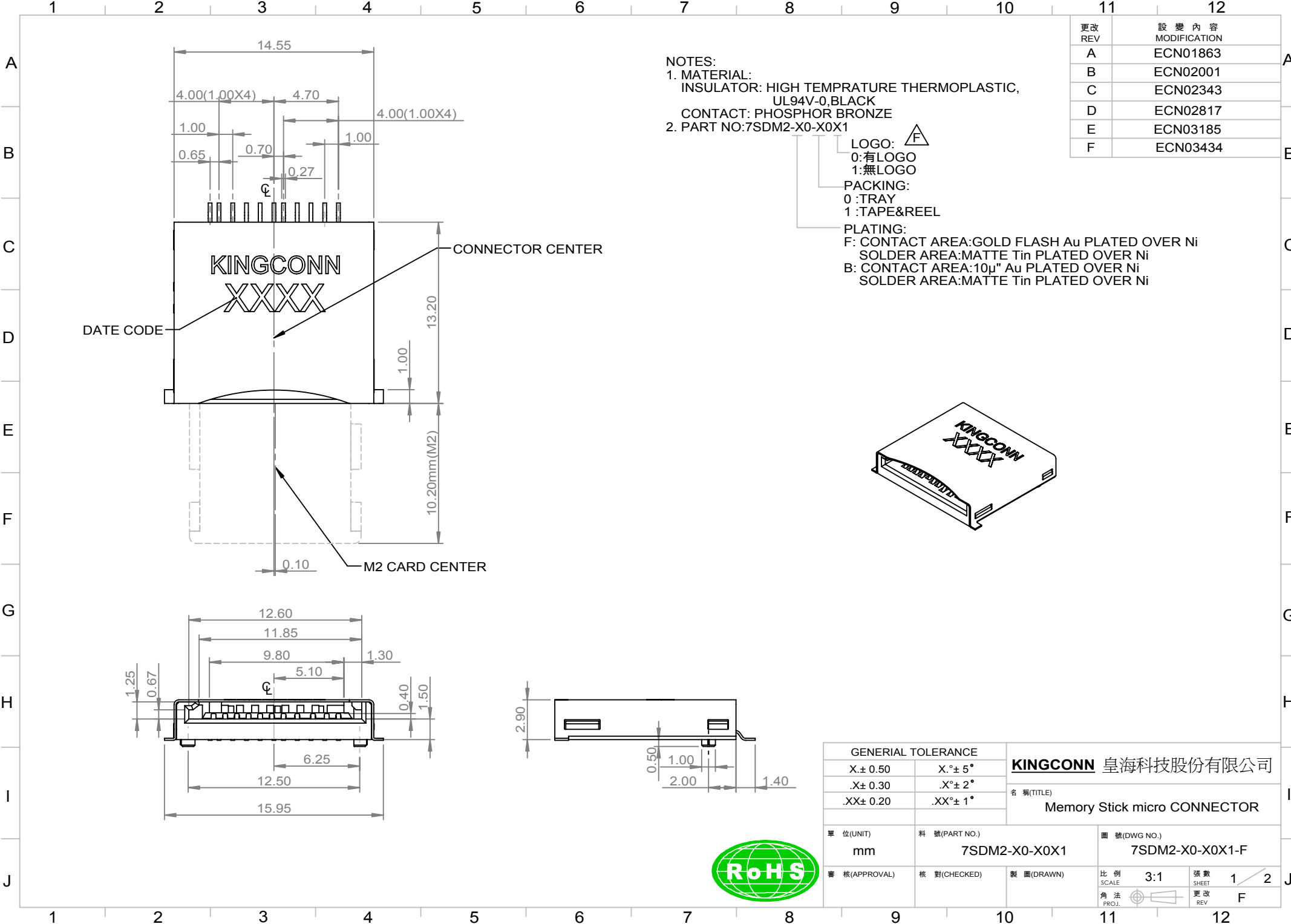
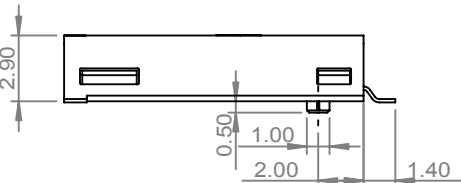
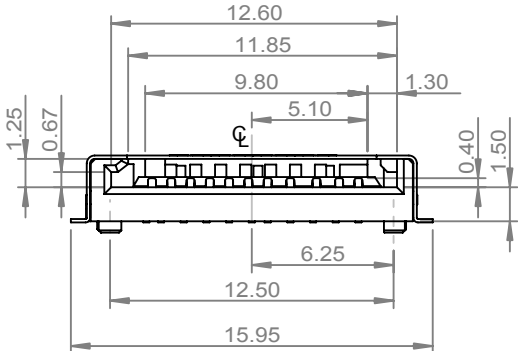
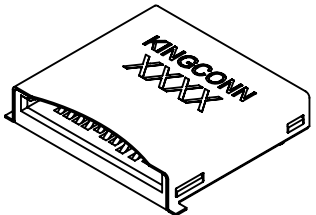




NOTES:
1. MATERIAL:
INSULATOR: HIGH TEMPRATURE THERMOPLASTIC,
UL94V-0,BLACK
CONTACT: PHOSPHOR BRONZE
2. PART NO:7SDM2-X0-X0X1

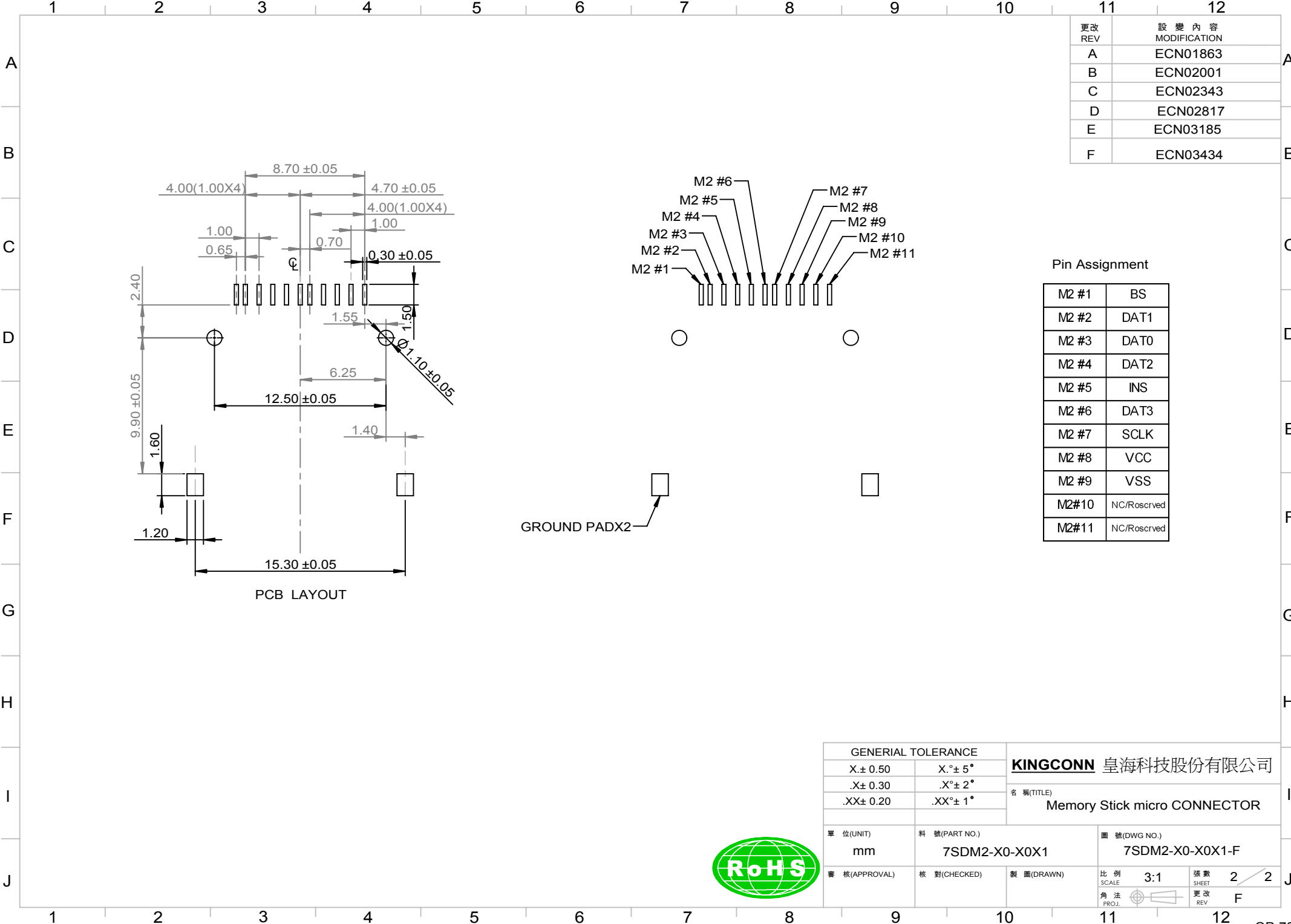
LOGO: 
0:有LOGO
1:無LOGO
PACKING:
0 :TRAY
1 :TAPE&REEL
PLATING:
F: CONTACT AREA:GOLD FLASH Au PLATED OVER Ni
SOLDER AREA:MATTE Tin PLATED OVER Ni
B: CONTACT AREA:10μ" Au PLATED OVER Ni
SOLDER AREA:MATTE Tin PLATED OVER Ni

更改 REV	設 變 內 容 MODIFICATION
A	ECN01863
B	ECN02001
C	ECN02343
D	ECN02817
E	ECN03185
F	ECN03434



GENERAL TOLERANCE		名 稱(TITLE) KINGCONN 皇海科技股份有限公司 Memory Stick micro CONNECTOR	
X.± 0.50	X.°± 5°		
.X± 0.30	.X°± 2°		
.XX± 0.20	.XX°± 1°	圖 號(DWG NO.) 7SDM2-X0-X0X1-F	
單 位(UNIT) mm	料 號(PART NO.) 7SDM2-X0-X0X1	比 例 SCALE 3:1	張 數 SHEET 1 / 2
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	角 法 PROJ. 更改 REV F





更改 REV	設 變 內 容 MODIFICATION
A	ECN01863
B	ECN02001
C	ECN02343
D	ECN02817
E	ECN03185
F	ECN03434

Pin Assignment

M2 #1	BS
M2 #2	DAT1
M2 #3	DAT0
M2 #4	DAT2
M2 #5	INS
M2 #6	DAT3
M2 #7	SCLK
M2 #8	VCC
M2 #9	VSS
M2 #10	NC/Roscrved
M2 #11	NC/Roscrved

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司 名 稱(TITLE) Memory Stick micro CONNECTOR	
X ± 0.50	X ° ± 5°		
.X ± 0.30	.X ° ± 2°		
.XX ± 0.20	.XX ° ± 1°		
單 位(UNIT) mm	料 號(PART NO.) 7SDM2-X0-X0X1	圖 號(DWG NO.) 7SDM2-X0-X0X1-F	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 3:1 張 數 SHEET 2 / 2 更 改 REV F

